

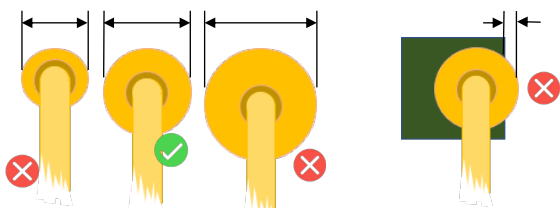
Advanced Wire-Bond Inspection

The inspection of sub 20um wire-bonds can be one of the most challenging tasks for any automated inspection system. Inspection systems need to measure the positions, rotations of all dies and then in real-time calculate the new bond and wire locations. In addition, inspections need to be performed with at the highest accuracy while keeping up with production UPH requirements.

Only MVPs 900 Series and 2030 systems can perform these tasks and meet spec's including mil-specs 883 and 750.

MVP's High-Resolution Optics and Proprietary Algorithms Provide Capability for:

Bond Deformations, Positions, Shorts Measured With High-Resolution Optics

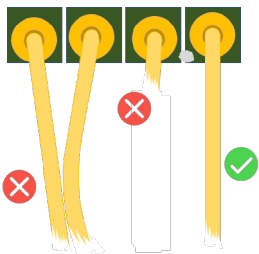


MVP's optics can provide sub-micron accuracy with lighting that allows us to image the most difficult bonds.

Bond Shape, Neck Position, Double Bond, Club Bond



Broken, Wire Sway, Position, FOD, FM

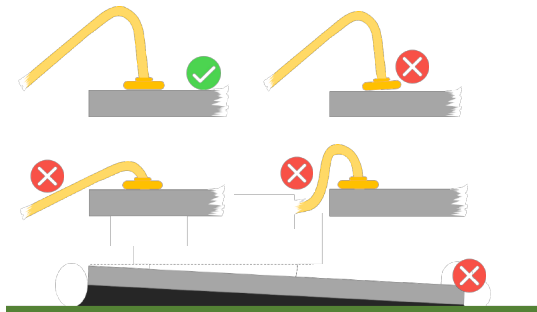


MVP 2030

MVP 900 Series

MVP's High-Resolution Laser Profilers and Proprietary 3D Algorithms Provide Capability for:

Wire Height, Sag, No Stick, Missing, Die Tilt, Bond Layer Thickness



Profilers allow measurement of wire peak to die surface or substrate and measurement of exact tilt of die surface.